#### SN74CBT16800 20-BIT FET BUS SWITCH WITH PRECHARGED OUTPUTS SCDS090 – MAY 1999

- **5-**Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- B-Port Outputs Are Precharged by Bias Voltage to Minimize Signal Distortion During Live Insertion
- Package Options Include Plastic Thin Shrink Small-Outline (DGG) and Thin Very Small-Outline (DGV) Packages

#### description

The SN74CBT16800 provides 20 bits of high-speed TTL-compatible bus switching. The low on-state resistance of the switch allows connections to be made with minimal propagation delay. The device also precharges the B port to a user-selectable bias voltage (BIASV) to minimize live-insertion noise.

The device is organized as dual 10-bit bus switches with separate output-enable ( $\overline{OE}$ ) inputs. It can be used as two 10-bit bus switches or one 20-bit bus switch. When  $\overline{OE}$  is low, the associated 10-bit bus switch is on and port A is connected to port B. When  $\overline{OE}$  is high, the switch is open, the high-impedance state exists between the two ports, and port B is precharged to BIASV through the equivalent of a 10-k $\Omega$  resistor.

To ensure the high-impedance state during power up or power down,  $\overline{\text{OE}}$  should be tied to V<sub>CC</sub> through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN74CBT16800 is characterized for operation from –40°C to 85°C.

FUNCTION TABL	E
(each 10-bit bus swi	tch)

INPUT OE	FUNCTION
L	A port = B port
н	A port = Z B port = BIASV



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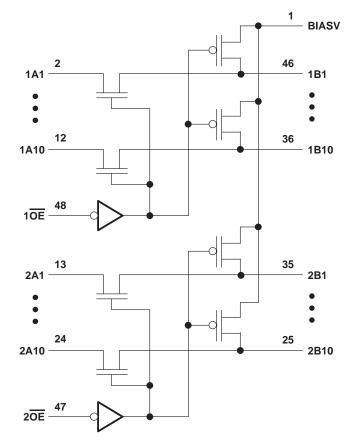


(TOP VIEW)						
BIASV [ 1A1 [ 1A2 ] 1A3 [ 1A4 [ 1A5 ] 1A4 [ 1A5 ] 1A6 [ 1A7 ] 1A8 [ 1A9 ] 1A10 [ 2A1 ] 2A2 [ VCC ] 2A3 [ GND ]	(TOP V 1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18	48 47 46 45 44 43 42 41 40 39 38 37 36 35 34 33 32 31	1 <u>OE</u> 2 OE 1 B1 1 B2 1 B3 1 B4 1 B5 ] GND 1 B6 1 B7 1 B8 1 B9 1 B10 2 B1 2 B2 2 B3 ] GND 2 B4			
GND	17	32	GND			
2A4 [ 2A5 [ 2A6 [ 2A7 [ 2A8 [	19 20 21 22	30 29 28 27	2B5 2B6 2B7 2B8			
2A9 [ 2A10 [	23 24	26 25	2B9 2B10			

DGG OR DGV PACKAGE

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### logic diagram (positive logic)



### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0)		0.5 V to 7 V 0.5 V to 7 V 128 mA 50 mA
Package thermal impedance, θ <sub>JA</sub> (see Note 2): DGG package	Package thermal impedance, θ <sub>JA</sub> (see Note 2): DGG package DGV package	

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51.



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#### recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
Vcc	Supply voltage	4	5.5	V
BIASV	Supply voltage	1.3	VCC	V
VIH	High-level control input voltage	2		V
VIL	Low-level control input voltage		0.8	V
Т <sub>А</sub>	Operating free-air temperature	-40	85	°C

NOTE 3: All unused control inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to TI application report Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

#### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS			MIN	TYP <sup>†</sup>	MAX	UNIT
VIK		V <sub>CC</sub> = 4.5 V,	lı = -18 mA				-1.2	V
Ц		V <sub>CC</sub> = 5.5 V,	$V_I = 5.5 \text{ V or GND}$				±5	μA
IO		V <sub>CC</sub> = 4.5 V,	BIASV = 2.4 V,	V <sub>O</sub> = 0	0.25			mA
ICC	-	V <sub>CC</sub> = 5.5 V,	l <sub>O</sub> = 0,	$V_{I} = V_{CC}$ or GND			50	μA
∆lcc‡	Control inputs	V <sub>CC</sub> = 3.6 V,	One input at 2.7 V,	Other inputs at $V_{CC}$ or GND			2.5	mA
Ci	Control inputs	V <sub>I</sub> = 3 V or 0						pF
Cio(OFF)		$V_{O} = 3 V \text{ or } 0,$	$\overline{OE} = V_{CC}$					pF
r <sub>on</sub> §		$V_{CC} = 4 V,$ TYP at $V_{CC} = 4 V$	V <sub>I</sub> = 2.4 V,	lj = 15 mA				
			C = 4.5 V VI = 0	II = 64 mA				Ω
		$V_{CC} = 4.5 V$		II = 30 mA				
		V <sub>I</sub> =	V <sub>I</sub> = 2.4 V,	lj = 15 mA				

<sup>†</sup> All typical values are at  $V_{CC} = 5 V$  (unless otherwise noted),  $T_A = 25^{\circ}C$ .

<sup>‡</sup>This is the increase in supply current for each input that is at the specified TTL voltage level rather than V<sub>CC</sub> or GND.

§ Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

#### switching characteristics over recommended operating free-air temperature range, CL = 50 pF (unless otherwise noted) (see Figure 1)

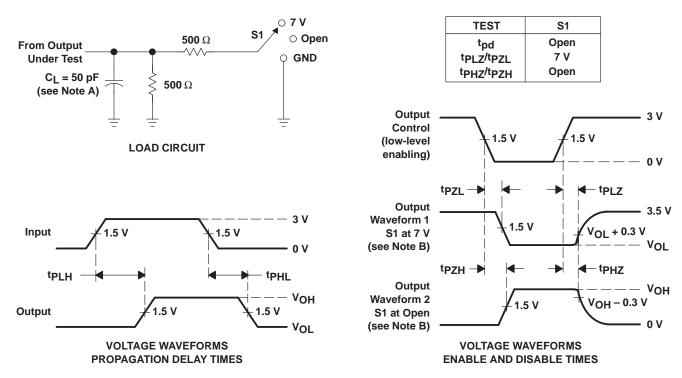
PARAMETER	TEST CONDITIONS	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 4 V		V <sub>CC</sub> = 5 V ± 0.5 V		UNIT
	CONDITIONS			MIN	MAX	MIN	MAX	
tpd¶		A or B	B or A					ns
<sup>t</sup> PZH	BIASV = GND	ŌĒ	A or B					20
<sup>t</sup> PZL	BIASV = 3 V	OE	AUB					ns
<sup>t</sup> PHZ	BIASV = GND	OE	A or B					
<sup>t</sup> PLZ	BIASV = 3 V	OE	AUB					ns

The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).



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#### PARAMETER MEASUREMENT INFORMATION

NOTES: A. CL includes probe and jig capacitance.

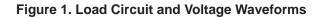
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control. C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz, Z<sub>O</sub> = 50  $\Omega$ , t<sub>f</sub>  $\leq$  2.5 ns, t<sub>f</sub>  $\leq$  2.5 ns.

D. The outputs are measured one at a time with one transition per measurement.

E. tpLz and tpHz are the same as tdis.

F. tpzL and tpzH are the same as ten.

G. tPLH and tPHL are the same as tpd.





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